

1.1W Audio Power Amplifier with Shutdown Mode

FEATURES

- No output coupling capacitors, bootstrap capacitors, or snubber circuits are necessary
- Small Outline (SOP) packaging
- Compatible with PC power supplies
- Thermal shutdown protection circuitry
- Unity-gain stable
- External gain configuration capability



ORDERING INFORMATION

DEVICE	Package Type	MARKING	Packing	Packing Qty
LM4861N	DIP-8	LM4861	TUBE	2000pcs/Box
LM4861M/TR	SOP-8	LM4861	REEL	2500pcs/Reel
LM4861MM/TR	MSOP-8	LM4861	REEL	3000pcs/Reel
LM4861ME/TR	ESOP-8	LM4861	REEL	2500pcs/Reel
LM4861DQ2/TR	DFN-8 2*2	LM4861	REEL	4000pcs/Reel
LM4861MME/TR	EMSOP-8	LM4861	REEL	3000pcs/Reel

DESCRIPTION

The LM4861 is a bridge-connected audio power amplifier capable of delivering 1.1W of continuous average power to an 8Ω load with 1% THD+N using a 5V power supply. Boomer audio power amplifiers were designed specifically to provide high quality output power with a minimal amount of external components using surface mount packaging. Since the LM4861 does not require output coupling capacitors, bootstrap capacitors, or snubber networks, it is optimally suited for low-power portable systems.

The LM4861 features an externally controlled, low-power consumption shutdown mode, as well as an internal thermal shutdown protection mechanism.

The unity-gain stable LM4861 can be configured by external gain-setting resistors for differential gains of up to 10 without the use of external compensation components. Higher gains may be achieved with suitable compensation.

APPLICATIONS

- Personal computers
- Portable consumer products
- Self-powered speakers
- Toys and games

KEY SPECIFICATIONS

- THD+N for 1kHz at 1W continuous average output power into 8Ω 1.0% (max)
- Output power at 10% THD+N at 1kHz into 8Ω 1.5 W (typ)
- Shutdown Current 0.6μA (typ)

CONNECTION DIAGRAM



TYPICAL APPLICATION

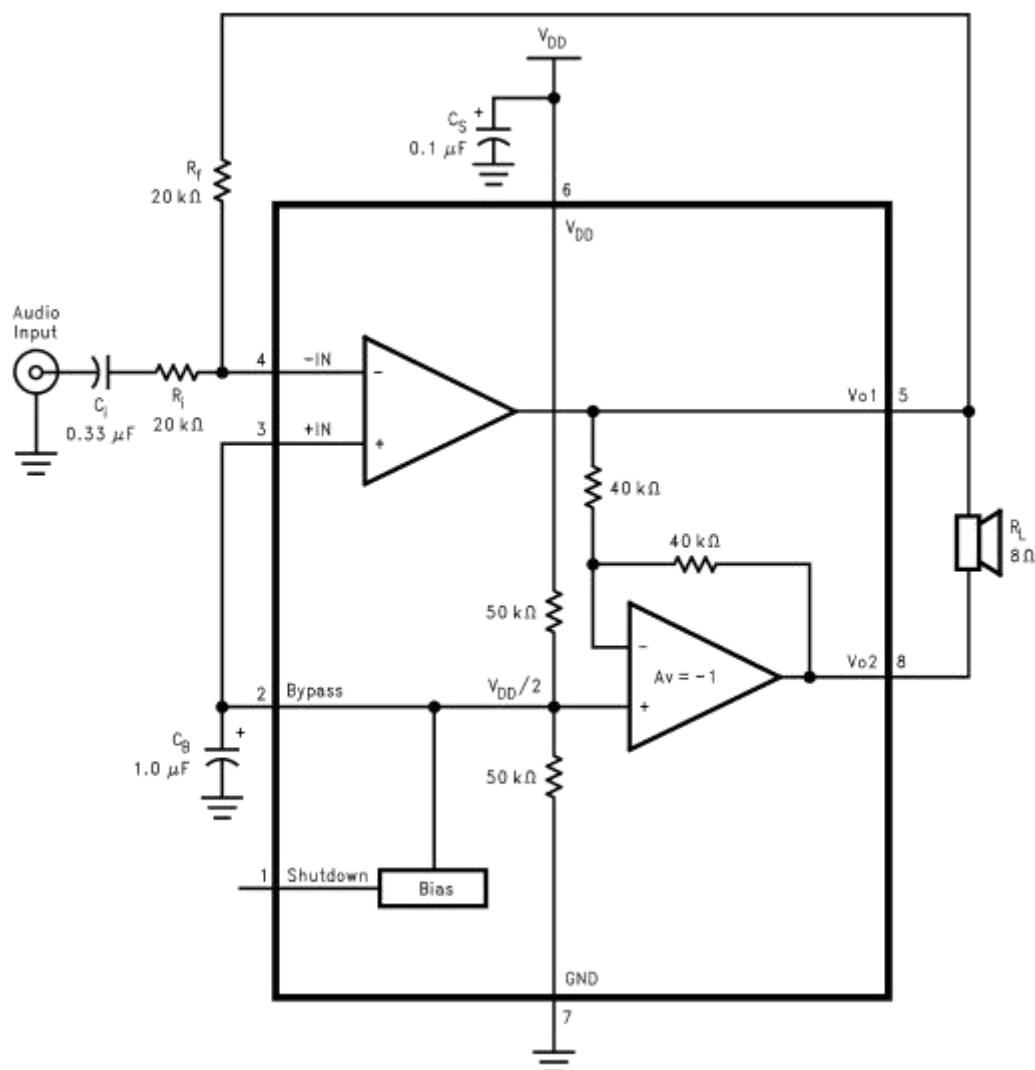


Figure 2. Typical Audio Amplifier Application Circuit



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS

Conditions	Limit
Supply Voltage	6.0V
Storage Temperature	-65°C to +150°C
Input Voltage	-0.3V to $V_{DD} + 0.3V$
Power Dissipation ⁽³⁾	Internally limited
ESD Susceptibility ⁽⁴⁾	3000V
ESD Susceptibility ⁽⁵⁾	250V
Junction Temperature	150°C
Lead Temperature (Soldering, 10 seconds)	260°C

1. Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance..
2. The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature T_A . The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4861, $T_{JMAX} = 150^\circ\text{C}$, and the typical junction-to-ambient thermal resistance, when board mounted, is 140°C/W .
3. Human body model, 100pF discharged through a 1.5k Ω resistor.
4. Machine Model, 220pF–240pF discharged through all pins.

OPERATING RATINGS

Conditions		Limit
Temperature Range	$T_{MIN} \leq T_A \leq T_{MAX}$	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Supply Voltage		$2.5V \leq V_{DD} \leq 5.5V$
Thermal Resistance	θ_{JC} (typ)—SOP	35°C/W
	θ_{JA} (typ)—SOP	140°C/W
	θ_{JC} (typ)—DIP	37°C/W
	θ_{JA} (typ)—DIP	107°C/W

ELECTRICAL CHARACTERISTICS

The following specifications apply for $V_{DD} = 5V$, unless otherwise specified. Limits apply for $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	LM4861		Units (Limits)
			Typical ⁽³⁾	Limit ⁽⁴⁾	
V_{DD}	Supply Voltage			2.5 5.5	V (min) V (max)
I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V, I_O = 0A$ ⁽⁵⁾	6.5	10.0	mA (max)
I_{SD}	Shutdown Current	$V_{SHUTDOWN} = V_{DD}$	0.6	10.0	μA (max)
V_{OS}	Output Offset Voltage	$V_{IN} = 0V$	5.0	50.0	mV (max)
P_O	Output Power	THD = 1% (max); $f = 1$ kHz	1.1	1.0	W (min)
THD+N	Total Harmonic Distortion + Noise	$P_O = 1W_{rms}$; $20\text{ Hz} \leq f \leq 20\text{ kHz}$	0.72		%
PSRR	Power Supply Rejection Ratio	$V_{DD} = 4.9V$ to $5.1V$	65		dB

1. All voltages are measured with respect to the ground pin, unless otherwise specified.
2. Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
3. Typicals are measured at $25^\circ C$ and represent the parametric norm.
4. Limits are specified to TI's AOQL (Average Outgoing Quality Level).
5. The quiescent power supply current depends on the offset voltage when a practical load is connected to the amplifier.

HIGH GAIN APPLICATION CIRCUIT

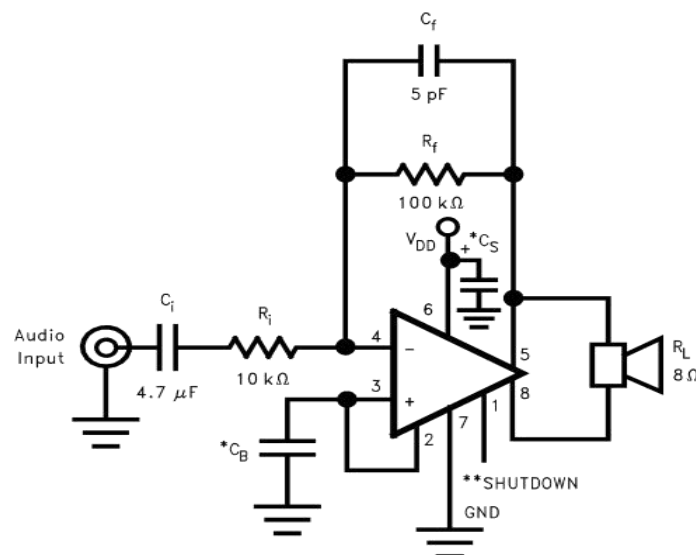
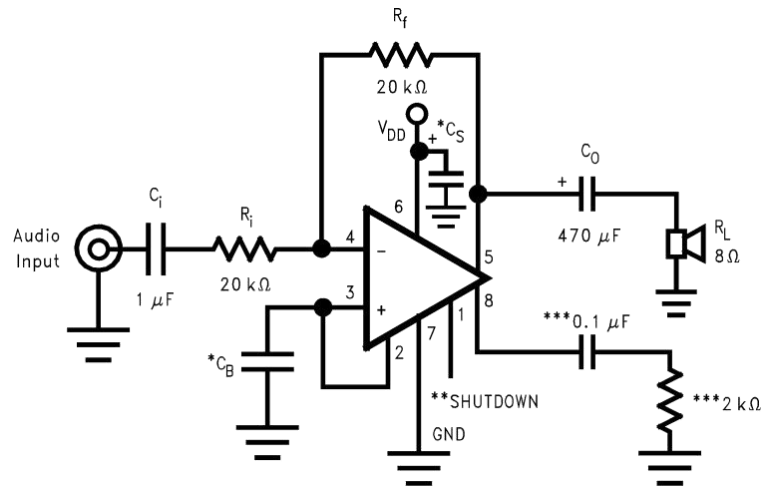


Figure 3. Audio Amplifier with $A_{VD}=20$

SINGLE ENDED APPLICATION CIRCUIT



*CS and CB size depend on specific application requirements and constraints. Typical values of CS and CB are 0.1 μF.

**Pin 1 should be connected to VDD to disable the amplifier or to GND to enable the amplifier. This pin should not be left floating.

***These components create a “dummy” load for pin 8 for stability purposes.

Figure 4. Single-Ended Amplifier with $A_v=-1$

EXTERNAL COMPONENTS DESCRIPTION

(Figure 2 and Figure 3)

Components	Functional Description
1. R_i	Inverting input resistance which sets the closed-loop gain in conjunction with R_f . This resistor also forms a high passfilter with C_i at $f_c = 1 / (2\pi R_i C_i)$.
2. C_i	Input coupling capacitor which blocks DC voltage at the amplifier's input terminals. Also creates a high pass filter with R_i at $f_c = 1 / (2\pi R_i C_i)$.
3. R_f	Feedback resistance which sets closed-loop gain in conjunction with R_i .
4. C_s	Supply bypass capacitor which provides power supply filtering. Refer to for proper placement and selection of supplybypass capacitor.
5. C_b	Bypass pin capacitor which provides half supply filtering. Refer to Application Information for proper placement andselection of bypass capacitor.
6. $C_f^{(1)}$	C_f in conjunction with R_f creates a low-pass filter which bandwidth limits the amplifier and prevents possible highfrequency oscillation bursts. $f_c = 1 / (2\pi R_f C_f)$

(1) Optional component dependent upon specific design requirements. Refer to Application Information for more information.

TYPICAL PERFORMANCE CHARACTERISTICS

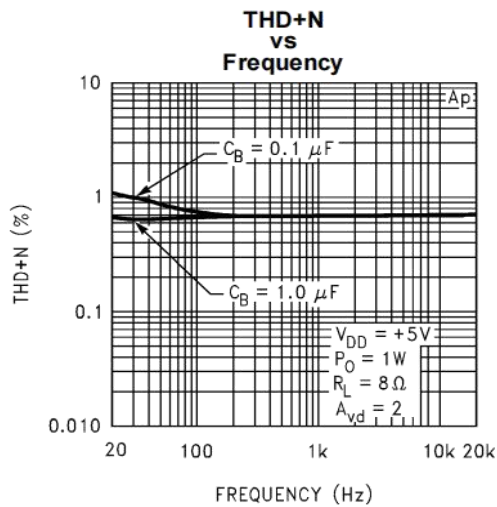


Figure 5.

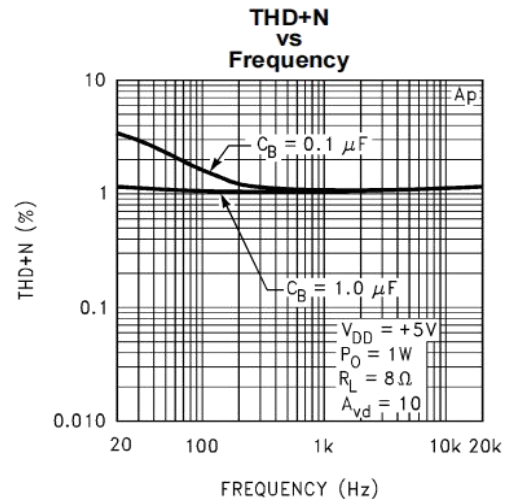


Figure 6.

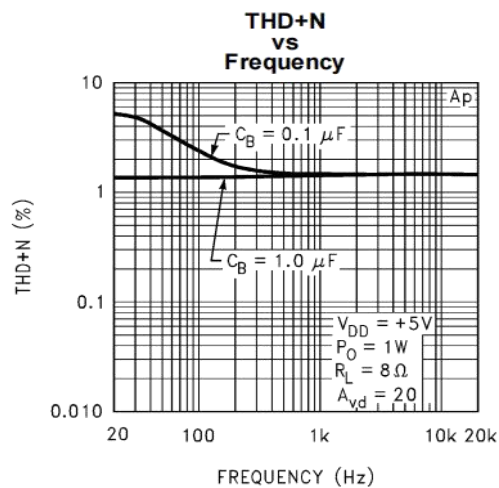


Figure 7.

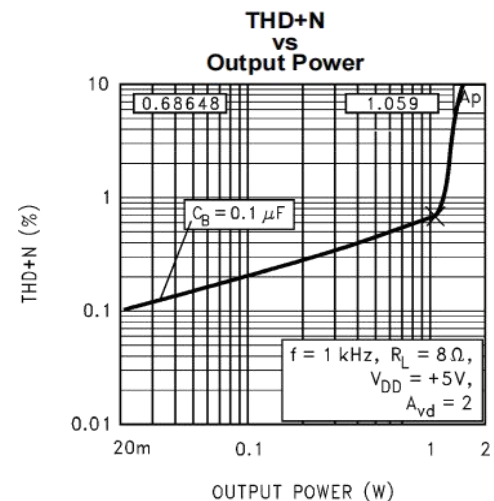


Figure 8.

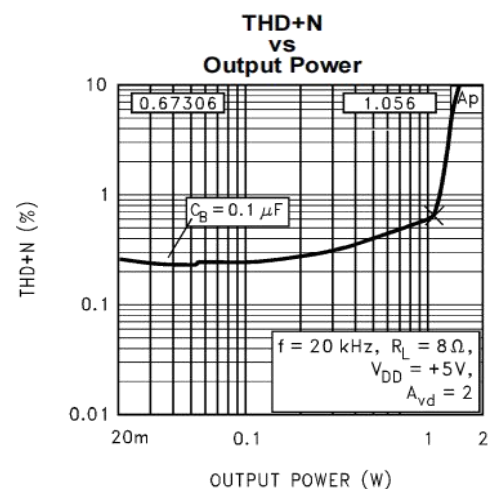


Figure 9.

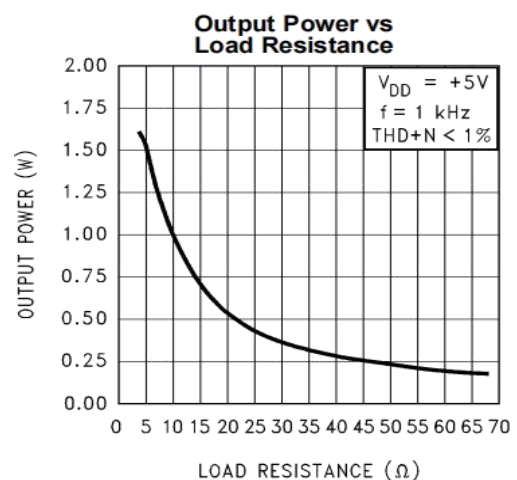


Figure 10.

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

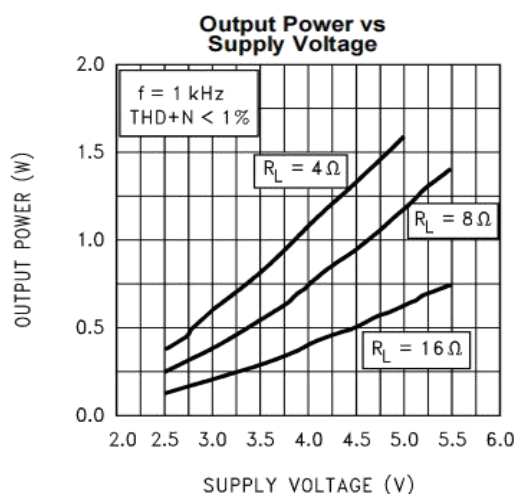


Figure 11.

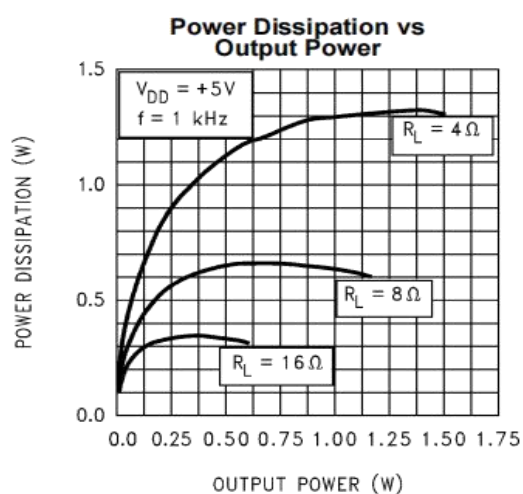


Figure 12.

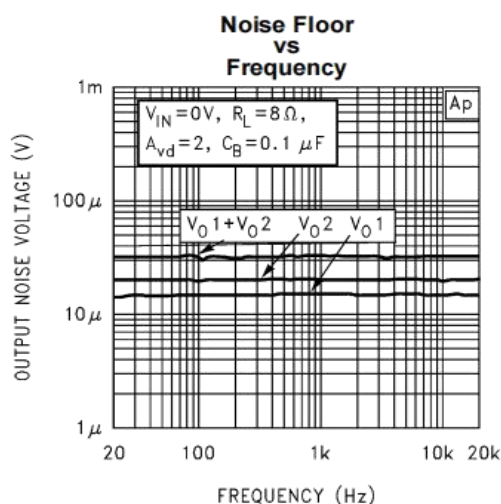


Figure 13.

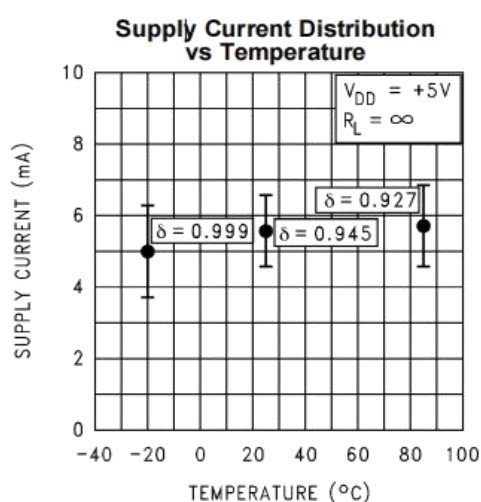


Figure 14.

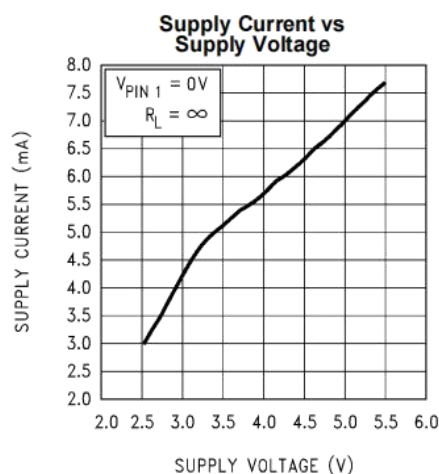


Figure 15.

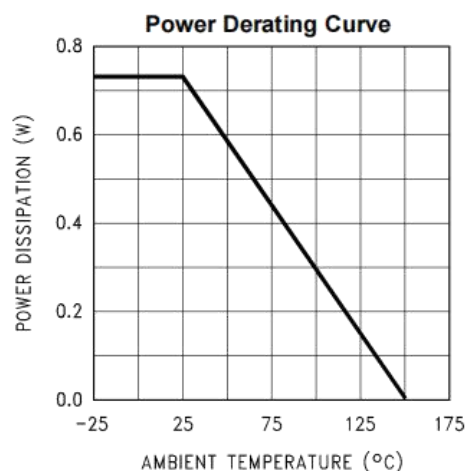


Figure 16.

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

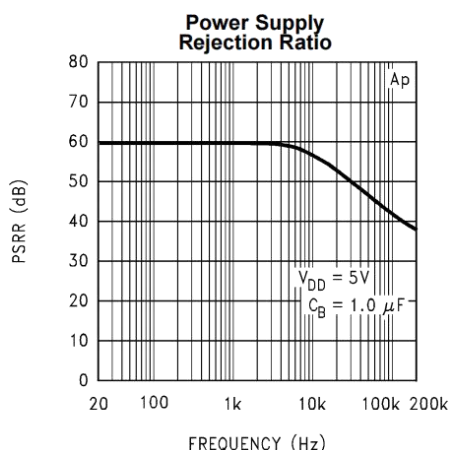


Figure 17.

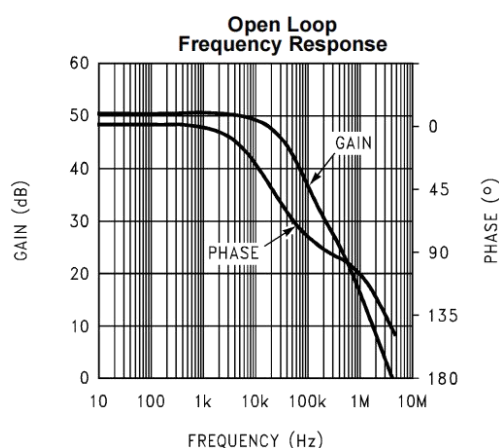


Figure 18.

APPLICATION INFORMATION

BRIDGE CONFIGURATION EXPLANATION

As shown in Figure 2, the LM4861 has two operational amplifiers internally, allowing for a few different amplifier configurations. The first amplifier's gain is externally configurable, while the second amplifier is internally fixed in a unity-gain, inverting configuration. The closed-loop gain of the first amplifier is set by selecting the ratio of R_f to R_i while the second amplifier's gain is fixed by the two internal 40kΩ resistors. Figure 2 shows that the output of amplifier one serves as the input to amplifier two which results in both amplifiers producing signals identical in magnitude, but out of phase 180°. Consequently, the differential gain for the IC is:

$$A_{vd} = 2 * (R_f / R_i) \quad (1)$$

By driving the load differentially through outputs VO1 and VO2, an amplifier configuration commonly referred to as “bridged mode” is established. Bridged mode operation is different from the classical single-ended amplifier configuration where one side of its load is connected to ground.

A bridge amplifier design has a few distinct advantages over the single-ended configuration, as it provides differential drive to the load, thus doubling output swing for a specified supply voltage. Consequently, four times the output power is possible as compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited or clipped. In order to choose an amplifier's closed-loop gain without causing excessive clipping which will damage high frequency transducers used in loudspeaker systems, please refer to AUDIO POWER AMPLIFIER DESIGN.

A bridge configuration, such as the one used in Boomer Audio Power Amplifiers, also creates a second advantage over single-ended amplifiers. Since the differential outputs, VO1 and VO2, are biased at half-supply, no net DC voltage exists across the load. This eliminates the need for an output coupling capacitor which is required in a single supply, single-ended amplifier configuration. Without an output coupling capacitor in a single supply, single-ended amplifier, the half-supply bias across the load would result in both increased internal IC power dissipation and also permanent loudspeaker damage. An output coupling capacitor forms a high pass filter with the load requiring that a large value such as 470μF be used with an 8Ω load to preserve low frequency response.

This combination does not produce a flat response down to 20Hz, but does offer a compromise between printed circuit board size and system cost, versus low frequency response.

POWER DISSIPATION

Power dissipation is a major concern when designing a successful amplifier, whether the amplifier is bridged or single-ended. A direct consequence of the increased power delivered to the load by a bridge amplifier is an increase in internal power dissipation. Equation 3 states the maximum power dissipation point for a bridge amplifier operating at a given supply voltage and driving a specified output load.

$$P_{DMAX} = 4 \cdot (V_{DD})^2 / (2\pi^2 R_L) \quad (2)$$

Since the LM4861 has two operational amplifiers in one package, the maximum internal power dissipation is 4 times that of a single-ended amplifier. Even with this substantial increase in power dissipation, the LM4861 does not require heatsinking. From Equation 3, assuming a 5V power supply and an 8Ω load, the maximum power dissipation point is 625mW. The maximum power dissipation point obtained from Equation 3 must not be greater than the power dissipation that results from Equation 3:

$$P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA} \quad (3)$$

For the LM4861 surface mount package, $\theta_{JA} = 140^\circ\text{C/W}$ and $T_{JMAX} = 150^\circ\text{C}$. Depending on the ambient temperature, T_A , of the system surroundings, Equation 3 can be used to find the maximum internal power dissipation supported by the IC packaging. If the result of Equation 3 is greater than that of Equation 3, then either the supply voltage must be decreased or the load impedance increased. For the typical application of a 5V power supply, with an 8Ω load, the maximum ambient temperature possible without violating the maximum junction temperature is approximately 62.5°C provided that device operation is around the maximum power dissipation point. Power dissipation is a function of output power and thus, if typical operation is not around the maximum power dissipation point, the ambient temperature can be increased. Refer to the Typical Performance Characteristics curves for power dissipation information for lower output powers.

POWER SUPPLY BYPASSING

As with any power amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. The capacitor location on both the bypass and power supply pins should be as close to the device as possible. As displayed in the Typical Performance Characteristics, the effect of a larger half supply bypass capacitor is improved low frequency THD+N due to increased half-supply stability. Typical applications employ a 5V regulator with 10μF and a 0.1μF bypass capacitors which aid in supply stability, but do not eliminate the need for bypassing the supply nodes of the LM4861. The selection of bypass capacitors, especially CB, is thus dependant upon desired low frequency THD+N, system cost, and size constraints.

SHUTDOWN FUNCTION

In order to reduce power consumption while not in use, the LM4861 contains a shutdown pin to externally turn off the amplifier's bias circuitry. The shutdown feature turns the amplifier off when a logic high is placed on the shutdown pin. Upon going into shutdown, the output is immediately disconnected from the speaker. A typical quiescent current of 0.6μA results when the supply voltage is applied to the shutdown pin. In many applications, a microcontroller or microprocessor output is used to control the shutdown circuitry which provides a quick, smooth transition into shutdown. Another solution is to use a single-pole, single-throw switch that when closed, is connected to ground and enables the amplifier. If the switch is open, then a soft pull-up resistor of 47kΩ will

disable the LM4861. There are no soft pull-down resistors inside the LM4861, so a definite shutdown pin voltage must be applied externally, or the internal logic gate will be left floating which could disable the amplifier unexpectedly.

HIGHER GAIN AUDIO AMPLIFIER

The LM4861 is unity-gain stable and requires no external components besides gain-setting resistors, an input coupling capacitor, and proper supply bypassing in the typical application. However, if a closed-loop differential gain of greater than 10 is required, a feedback capacitor may be needed, as shown in Figure 3, to bandwidth limit the amplifier. This feedback capacitor creates a low pass filter that eliminates possible high frequency oscillations. Care should be taken when calculating the -3dB frequency in that an incorrect combination of R_f and C_f will cause rolloff before 20kHz . A typical combination of feedback resistor and capacitor that will not produce audio band high frequency rolloff is $R_f = 100\text{k}\Omega$ and $C_f = 5\text{pF}$. These components result in a -3dB point of approximately 320kHz . Once the differential gain of the amplifier has been calculated, a choice of R_f will result, and C_f can then be calculated from the formula stated in External Components Description .

VOICE-BAND AUDIO AMPLIFIER

Many applications, such as telephony, only require a voice-band frequency response. Such an application usually requires a flat frequency response from 300Hz to 3.5kHz . By adjusting the component values of Figure 3, this common application requirement can be implemented. The combination of R_i and C_i form a highpass filter while R_f and C_f form a lowpass filter. Using the typical voice-band frequency range, with a passband differential gain of approximately 100, the following values of R_i , C_i , R_f , and C_f follow from the equations stated in External Components Description .

$$R_i = 10\text{k}\Omega, R_f = 510\text{k}\Omega, C_i = 0.22\mu\text{F}, \text{ and } C_f = 15\text{pF} \quad (4)$$

Five times away from a -3dB point is 0.17dB down from the flatband response. With this selection of components, the resulting -3dB points, f_L and f_H , are 72Hz and 20kHz , respectively, resulting in a flatband frequency response of better than $\pm 0.25\text{dB}$ with a rolloff of 6dB/octave outside of the passband. If a steeper rolloff is required, other common bandpass filtering techniques can be used to achieve higher order filters.

SINGLE-ENDED AUDIO AMPLIFIER

Although the typical application for the LM4861 is a bridged monoaural amp, it can also be used to drive a load singlendedly in applications, such as PC cards, which require that one side of the load is tied to ground.

Figure 4 shows a common single-ended application, where $VO1$ is used to drive the speaker. This output is coupled through a $470\mu\text{F}$ capacitor, which blocks the half-supply DC bias that exists in all single-supply amplifier configurations. This capacitor, designated CO in Figure 4, in conjunction with RL , forms a highpass filter. The -3dB point of this high pass filter is $1/(2\pi RLCO)$, so care should be taken to make sure that the product of RL and CO is large enough to pass low frequencies to the load. When driving an 8Ω load, and if a full audio spectrum reproduction is required, CO should be at least $470\mu\text{F}$. $VO2$, the output that is not used, is connected through a $0.1\mu\text{F}$ capacitor to a $2\text{k}\Omega$ load to prevent instability.

While such an instability will not affect the waveform of $VO1$, it is good design practice to load the second output.

AUDIO POWER AMPLIFIER DESIGN

Design a 1W / 8Ω Audio Amplifier

Given:	
Power Output	1 Wrms
Load Impedance	8Ω
Input Level	1 Vrms
Input Impedance	20 kΩ
Bandwidth	100 Hz–20 kHz ± 0.25 dB

A designer must first determine the needed supply rail to obtain the specified output power. By extrapolating from Figure 11 in Typical Performance Characteristics, the supply rail can be easily found. A second way to determine the minimum supply rail is to calculate the required V_{opeak} using Equation 5 and add the dropout voltage. Using this method, the minimum supply voltage would be ($V_{opeak} + V_{OD}$), where V_{OD} is typically 0.6V.

$$V_{opeak} = \sqrt{(2R_L P_O)} \quad (5)$$

For 1W of output power into an 8Ω load, the required V_{opeak} is 4.0V. A minimum supply rail of 4.6V results from adding V_{opeak} and V_{od} . But 4.6V is not a standard voltage that exists in many applications and for this reason, a supply rail of 5V is designated. Extra supply voltage creates dynamic headroom that allows the LM4861 to reproduce peaks in excess of 1W without clipping the signal. At this time, the designer must make sure that the power supply choice along with the output impedance does not violate the conditions explained in the POWER DISSIPATION.

Once the power dissipation equations have been addressed, the required differential gain can be determined from Equation 6.

$$A_{VD} \geq \sqrt{P_O P_L} / (V_{IN}) = V_{orms} / V_{inrms} \quad (6)$$

$$R_f / R_i = A_{VD} / 2 \quad (7)$$

From Equation 6, the minimum A_{vd} is 2.83: $A_{vd} = 3$

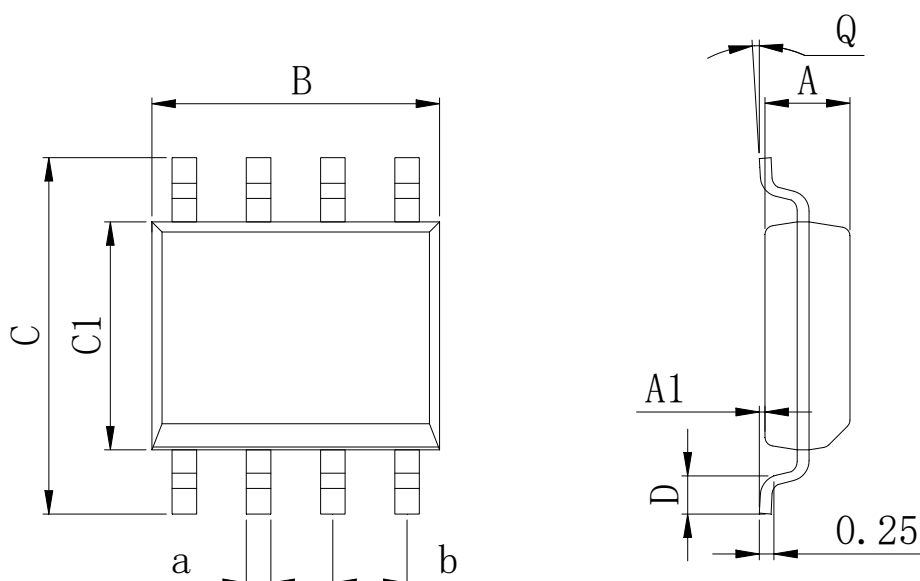
Since the desired input impedance was 20kΩ, and with a A_{vd} of 3, a ratio of 1:1.5 of R_f to R_i results in an allocation of $R_i = 20k\Omega$, $R_f = 30k\Omega$. The final design step is to address the bandwidth requirements which must be stated as a pair of -3dB frequency points. Five times away from a -3db point is 0.17dB down from passband response which is better than the required ±0.25dB specified. This fact results in a low and high frequency pole of 20Hz and 100kHz respectively. As stated in External Components Description, R_i in conjunction with C_i create a highpass filter.

$$C_i \geq 1 / (2\pi * 20k\Omega * 20Hz) = 0.397\mu F; \text{ use } 0.39\mu F. \quad (8)$$

The high frequency pole is determined by the product of the desired high frequency pole, f_H , and the differential gain, A_{vd} . With a $A_{vd} = 2$ and $f_H = 100kHz$, the resulting GBWP = 100kHz which is much smaller than the LM4861 GBWP of 4MHz. This figure displays that if a designer has a need to design an amplifier with a higher differential gain, the LM4861 can still be used without running into bandwidth problems.

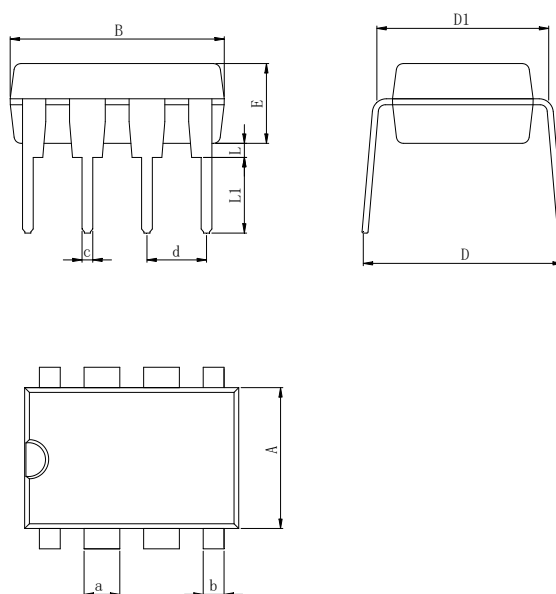
PHYSICAL DIMENSIONS

SOP-8



Dimensions In Millimeters(SOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

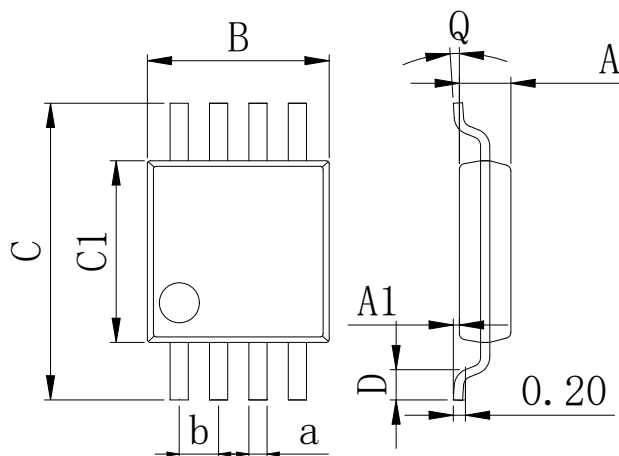
DIP-8



Dimensions In Millimeters(DIP-8)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

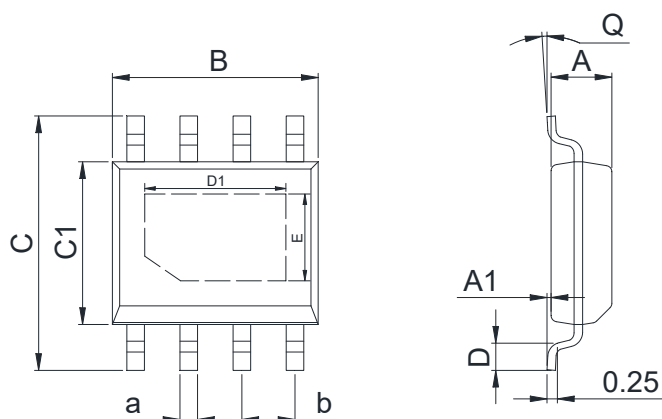
PHYSICAL DIMENSIONS

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	

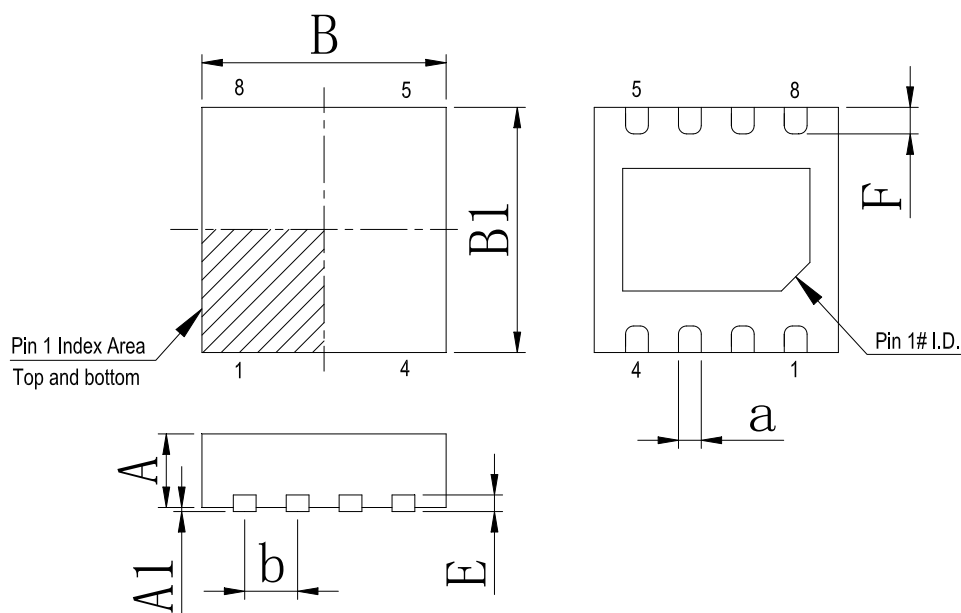
ESOP-8



Dimensions In Millimeters(ESOP-8)											
Symbol:	A	A1	B	C	C1	D	D1	E	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	3.20	2.31	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	3.40	2.51	8°	0.45	

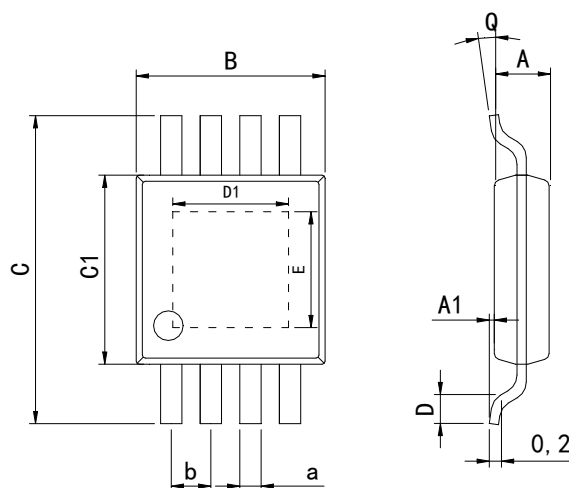
PHYSICAL DIMENSIONS

DFN-8 2*2



Dimensions In Millimeters(DFN-8 2*2)								
Symbol:	A	A1	B	B1	E	F	a	b
Min:	0.85	0	1.90	1.90	0.15	0.25	0.18	0.50TYP
Max:	0.95	0.05	2.10	2.10	0.25	0.45	0.30	

EMSOP-8



Dimensions In Millimeters(EMSOP-8)											
Symbol:	A	A1	B	C	C1	D	D1	E	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	1.8	1.5	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	2.1	2.0	8°	0.35	

REVISION HISTORY

REVISION NUMBER	DATE	REVISION	PAGE
V1.0	2012-9	New	1-16
V1.1	2015-8	Update encapsulation type、Updated DIP-8 dimension	1、 13
V1.2	2024-11	Update Lead Temperature	4

IMPORTANT STATEMENT:

Huaguan Semiconductor reserves the right to change its products and services without notice. Before ordering, the customer shall obtain the latest relevant information and verify whether the information is up to date and complete. Huaguan Semiconductor does not assume any responsibility or obligation for the altered documents.

Customers are responsible for complying with safety standards and taking safety measures when using Huaguan Semiconductor products for system design and machine manufacturing. You will bear all the following responsibilities: Select the appropriate Huaguan Semiconductor products for your application; Design, validate and test your application; Ensure that your application meets the appropriate standards and any other safety, security or other requirements. To avoid the occurrence of potential risks that may lead to personal injury or property loss.

Huaguan Semiconductor products have not been approved for applications in life support, military, aerospace and other fields, and Huaguan Semiconductor will not bear the consequences caused by the application of products in these fields. All problems, responsibilities and losses arising from the user's use beyond the applicable area of the product shall be borne by the user and have nothing to do with Huaguan Semiconductor, and the user shall not claim any compensation liability against Huaguan Semiconductor by the terms of this Agreement.

The technical and reliability data (including data sheets), design resources (including reference designs), application or other design suggestions, network tools, safety information and other resources provided for the performance of semiconductor products produced by Huaguan Semiconductor are not guaranteed to be free from defects and no warranty, express or implied, is made. The use of testing and other quality control technologies is limited to the quality assurance scope of Huaguan Semiconductor. Not all parameters of each device need to be tested.

The documentation of Huaguan Semiconductor authorizes you to use these resources only for developing the application of the product described in this document. You have no right to use any other Huaguan Semiconductor intellectual property rights or any third party intellectual property rights. It is strictly forbidden to make other copies or displays of these resources. You should fully compensate Huaguan Semiconductor and its agents for any claims, damages, costs, losses and debts caused by the use of these resources. Huaguan Semiconductor accepts no liability for any loss or damage caused by infringement.